



Material Content Data Sheet



Sales Product Name		BSP742R		Issued		29. August 2013		
MA#		MA000975730						
Package		PG-DSO-8-24		Weight*		83.23 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	1.539	1.85	1.85	18487	18487
leadframe	inorganic material	phosphorus	7723-14-0	0.009	0.01		108	
	non noble metal	zinc	7440-66-6	0.036	0.04		431	
	non noble metal	iron	7439-89-6	0.717	0.86		8617	
wire	non noble metal	copper	7440-50-8	29.121	34.99	35.90	349903	359059
	noble metal	gold	7440-57-5	0.471	0.57	0.57	5660	5660
	encapsulation	organic material	carbon black	1333-86-4	0.099	0.12		1184
plastics	plastics	epoxy resin	-	4.532	5.45		54456	
	inorganic material	silicondioxide	60676-86-0	44.632	53.62	59.19	536270	591910
leadfinish	non noble metal	tin	7440-31-5	0.814	0.98	0.98	9779	9779
plating	noble metal	silver	7440-22-4	0.650	0.78	0.78	7813	7813
glue	plastics	epoxy resin	-	0.106	0.13		1276	
	noble metal	silver	7440-22-4	0.501	0.60	0.73	6016	7292
*deviation	< 10%		Sum in total:			100.00		1000000

Important Remarks:

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